



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXAMINER: N. PAREKH)
3 APPLICANT: PETER ELENIUS, ET AL.)
4 SERIAL NO.: 09/575,298)
5 FILED: May 19, 2000)
6 FOR: "SOLDER BAR FOR HIGH POWER)
FLIP CHIPS")
7)
8)
9)

Art Unit 2811

TECHNOLOGY CENTER 2800

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Patents, Washington, D.C. 20231.


Marvin A. Glazer

October 24, 2002
Date

AMENDMENT

16 BOX CPA
17 Honorable Commissioner for Patents
Washington, D.C. 20231

18 Sir:

19 IN THE CLAIMS:

20 Please amend claim 16 as follows:

21 *Sub C* 
22 ~~16. A reflowable solder bar formed upon an upper surface of a first substrate, the first~~
23 ~~substrate having a first electrical contact, said reflowable solder bar being adapted to join the~~
24 ~~first electrical contact to a second electrical contact on a second substrate, said reflowable~~
25 ~~solder bar comprising in combination:~~

26 a. a first generally circular solder pad formed upon the upper surface of the first
27 substrate, the first generally circular solder pad having a center, and having a first
28 predetermined diameter D;